



Solder Paint EPB Sn100

- Solder paint EPB is a product specially developed at MBO laboratories.
- Using a flux base of stabilised mineral non-rosin flux and stable Tin Copper alloy powder.
- This paint confers excellent wetting on various metals (except chromium and aluminium).
- User friendly because of good thixotropic properties.

Physical Characteristics:

Composition: Tin : 99.3% - Copper : 0.7%
Metal content : ~80%

Melting point: 227°C

Density: ~ 7.3g/cm³

Viscosity: 135 +/- 15 Pa.s

Particle Size Distribution :

Particle Size	Min	Max
>75 microns	/	0.5
>45 microns	5	15
>25 microns	15	/
<25 microns	/	70*

Application:

The paint can be applied in a thin layer using a paint brush. Then heating is necessary to melt the solder. Please note that overheating will cause the flux to char and discolour.

Residues can be removed with a wet cloth or brush. Water cleaning will eliminate all residues.

The solder paint may be reflowed using various heating techniques to include heating with a blowtorch.

The suspension is stable during utilisation although settling can occur after a long storage in pots, in this case a slight mixing of the paint will be necessary before application.

Application Field:

Solder paint EPB may be used for various applications to include mechanical (automotive, boiler making, coach building, plumbing, model making) electrical (capacitors, resistors, fuses, general components) and electronic (tinning) as well as many others

Packaging/Storage:

Solder paint EPB is available in 500g and 1000g pots and or bottles.

The solder paint may be stored for up to 6 months between 5°C and 10°C and 3 months at room temperature (20°C to 25°C).